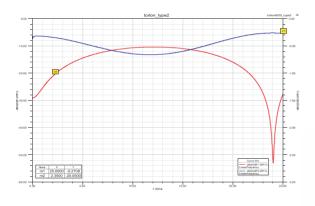
High Frequency Solutions

High frequency testing is mostly used for radio-frequency channels and wide-band transaction applications. The signal pin can be customized according to the electrical characteristics and testing environments of the client. For IC testing, we usually recommend ultra-short pins, coaxial probes, and PCRs to accommodate the different types of ICs.

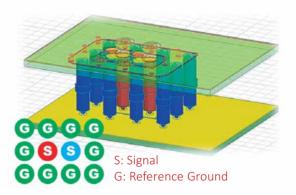
Design Concept



We have the ability to simulate 3D electromagnetic performance as well as S-parameters, inductance and impedance and by that improving SI characteristics.

Performance Simulation

CCP utilizes HFSS to simulate the pin performance in the sockets. This allows us to choose the best pin before designing a customized sockets.

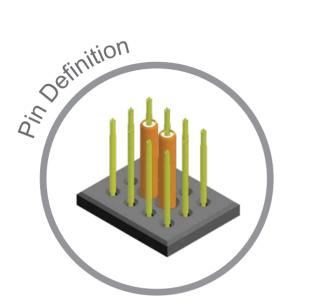




CCP has a dedicate high frequency lab that uses TDR, network analyzers and RF probe stations to measure the socket / pins actual performance and therby verifying the simulation results. These are all indispensable equipments for developing new high-class products.



Probe Specifications (Coaxial Probe)





High Frequency Solutions

Pin Definition

S Signal Probe G Ground Probe G G G G G G S S G

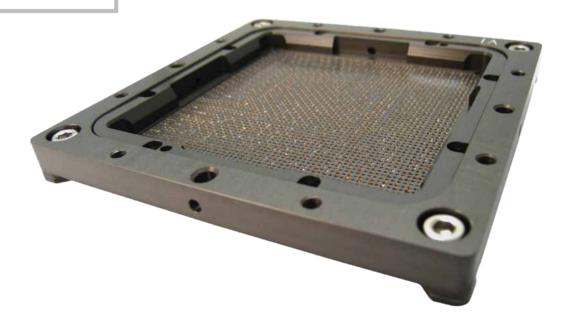
G

Application

Feature: High Speed / High Frequency DUT: Bluetooth / GPS / LTE / Wireless IC / 5G Packaging: BGA / CSP / QFN / QFP

Specification

Insertion Loss: -1dB @ >50 GHz Return Loss: -20dB @ >30 GHz Impedance: 50 Ohm Pitch: 0.65~1.00 mm



Probe Specifications (IC Test Probe)

Unit:mm; []:in

, 10031 0.080 [0.0110]. Ø0.280 0.0382 0.970 0.9484 0.0484 [0.0130]_ Ø0.330 [0.0110] Ø0.280 0.340 0.0102 [0.0051] Ø0.130

PE4-028DE09-01A0

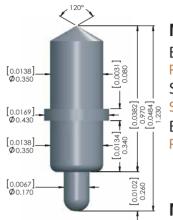
Material Barrel Pd alloy Spring SUS, Au plated Bottom Plunger BeCu, Au plated

Mechanical Spec.

Recommened Travel 0.18mm **Full Travel** 0.23mm Spring Force 15g±20%@0.18mm

Operating Temp. -55°C~150°C

PE4-035DE09-01H0



Material Barrel Pd alloy Spring SUS, Au plated **Bottom Plunger** Pd alloy

Mechanical Spec.

Recommened Travel 0.18mm Full Travel 0.23mm Spring Force 14g±20%@0.18mm Operating Temp. -55°C~150°C

Electrical Spec. S G G Pitch: 0.5mm Socket Material: Peek 1000

Current Rating 1A continuous Contact Resistance $<_{75m}\Omega(AVG)$ Characteristic Impedance 48.9Ω Insertion Loss -1dB>20GHz Return Loss -20dB>20GHz Time Delay 7.3 psec Loop Inductance 0.36 nH Capacitance 0.15 pF

Electrical Spec. Pitch: 0.5mm Socket Material: Peek 100



Current Rating 1A continuous Contact Resistance <75mΩ(AVG) Characteristic Impedance 37.4Ω Insertion Loss -1dB>20GHz Return Loss -20dB@7.62GHz Time Delay 7.48 psec Loop Inductance 0.28 nH Capacitance 0.2 pF

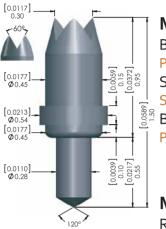


High Frequency Solutions

Probe Specifications (IC Test Probe)

Unit:mm; []:in

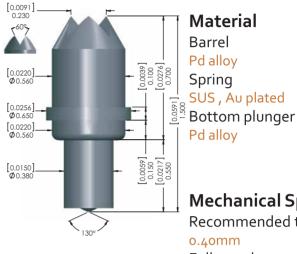
PE4-045EF09-01A0



Material Barrel Pd alloy Spring SUS , Au plated Bottom plunger Pd alloy

Mechanical Spec. Recommended travel 0.40mm Full travel 0.55mm Spring force 30g±20%@0.40mm Operating Temp. -55°C~150°C

PE4-056EF09-01H0



Mechanical Spec. Recommended travel 0.40mm Full travel 0.55mm Spring force 31g±20%@0.40mm Operating Temp.

-55°C~150°C

Electrical Spec.



Pitch: 0.65mm Socket Material: Peek 1000 Current Rating 1A continuous Contact Resistance $<75m\Omega(AVG)$ Characteristic Impedance 35.9Ω Insertion Loss -1dB>20GHzReturn Loss -2odB@5.54GHzTime Delay 8.6 psec Loop Inductance 0.31 nH Capacitance 0.24 pF





Current Rating 1A continuous Contact Resistance $<75m\Omega(AVG)$ Characteristic Impedance 29.7Ω Insertion Loss -1dB>20GHzReturn Loss -2odB@2.9GHzTime Delay 10.4psec Loop Inductance 0.31nHCapacitance 0.35pF